



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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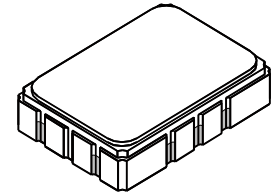


- *Designed for GPS Applications*
- *Quartz Temperature Stability*
- *Small Size*
- *Hermetic 7 x 5 mm Surface-mount Case*
- *Complies with Directive 2002/95/EC (RoHS)*



SF1131B

**266 MHz
SAW Filter**



SMP-03

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Suitable for lead-free soldering - Max. Soldering Profile	260°C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	f_C	1	266.01			MHz
Passband	Insertion Loss at f_C	IL			12.0	dB
		1 db Passband	BW_1	0.5		
	3 db Passband	BW_3	2.2		2.6	
	Amplitude Ripple over $f_C \pm 0.5$ MHz		1, 2			1.0
Group Delay Variation over $f_C \pm 1.1$ MHz	GDV				250	ns _{P-P}
Rejection	$f_C \pm 10$ MHz	1, 2, 3	50			dB
Operating Temperature Range	T_A	1	-30		+85	°C

Impedance Matching to 50Ω	External L-C match required to 50 ohms	
Case Style	6	SMP-03 7 x 5 mm Nominal Footprint
Lid Symbolization (YY = year, WW = week)		RFM SF1131B YYWW

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

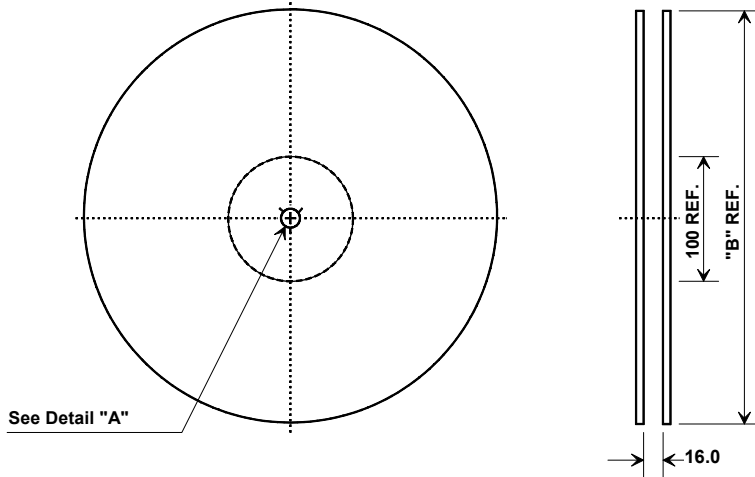
NOTES:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_C .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Tape and Reel Standard ANSI / EIA 481.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.

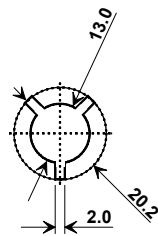
Electrical Connections

Connection	Terminals
Port 1	1, 10
Port 2	5, 6
Case Ground	All others

Tape and Reel Specifications

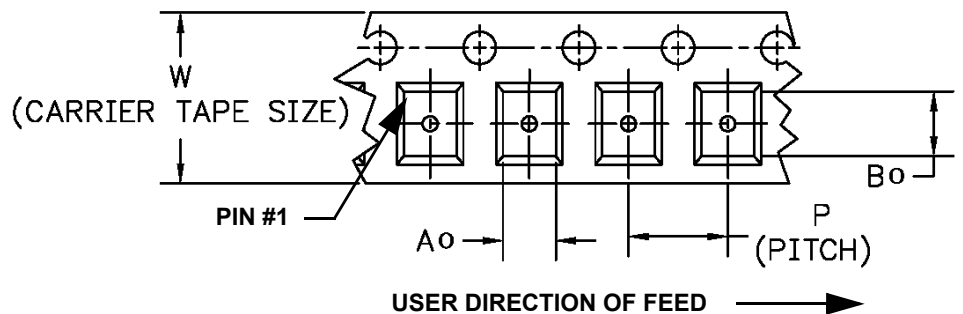
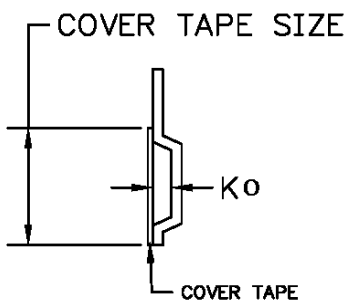


"B "		Quantity Per Reel
Nominal Size		
Inches	millimeters	
7	178	500
13	330	2000



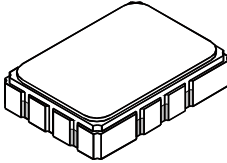
COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	5.5 mm
Bo	7.5 mm
Ko	2.0 mm
Pitch	8.0 mm
W	16.0 mm

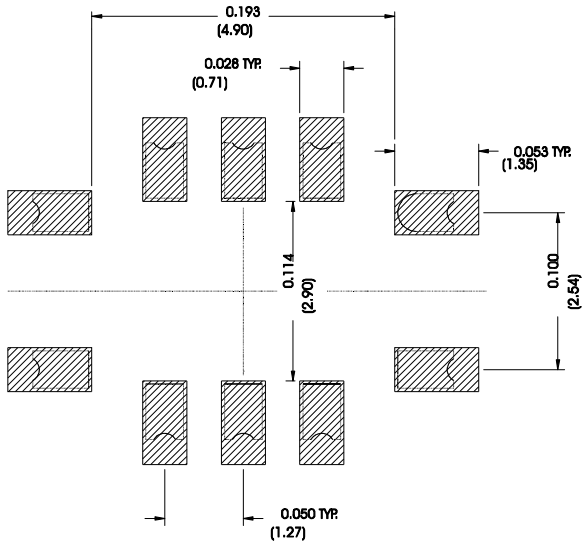


SMP-03 Case

10-Terminal Ceramic Surface-Mount Case 7 x 5 mm Nominal Footprint



Recommended PCB Footprint



Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D		0.60			0.024	
E		2.54			0.100	
H		1.0			0.039	
J		5.00			0.197	
K		3.00			0.118	
P		1.27			0.050	

Electrical Connections		
Connection		Terminals
Port 1	Input or Return	10
	Return or Input	1
Port 2	Output or Return	5
	Return or Output	6
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot

Materials	
Solder Pad Termination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	

